

28-02-07	Mechanical Properties I	6.1-6.12	NO QUIZ
05-03-07	Mechanical Properties II	6.1-6.12, 7.1-7.13	
07-03-07	Mechanical Properties III	7.1-7.13	WebCT Quiz
12-03-07	Mechanical Properties IV	8.1-8.15	
14-03-07	Mechanical Properties V	8.1-8.15	Tutorial Quizzes
19-03-07	Electrical Properties I	18.1-18.12	
21-03-07	Electrical Properties II	18.12-18.25	
26-03-07	CANCELLED - Election Day		
28-03-07	Ceramics, Plastics, Polymers		Tutorial Quizzes & WebCT
			Quiz
02-04-07	Thermal Properties	19.1-19.5 (Web)	
04-04-07	Optical Properties	21.1-21.14 (Web)	Tutorial Quizzes
09-04-07	CANCELLED – Easter Monday		
11-04-07	Review of Properties		

Chapter 18: Electrical Properties

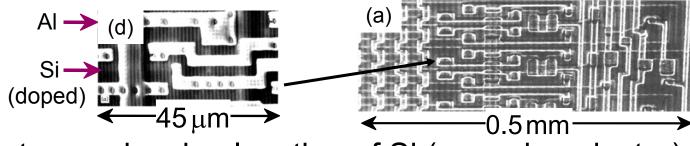
We will cover 18.1 – 18.13 and 18.15 – 18.23

TODAY

- How are electrical conductance and resistance characterized?
- What are the physical phenomena that distinguish conductors, semiconductors, and insulators?
- For metals, how is conductivity affected by imperfections, *T*, and deformation?
- For semiconductors, how is conductivity affected by impurities (doping) and *T*?

View of an Integrated Circuit

• Scanning electron microscope images of an IC:



A dot map showing location of Si (a semiconductor):
 -- Si shows up as light regions.

• A dot map showing location of AI (a conductor):

-- Al shows up as light regions.

insulators

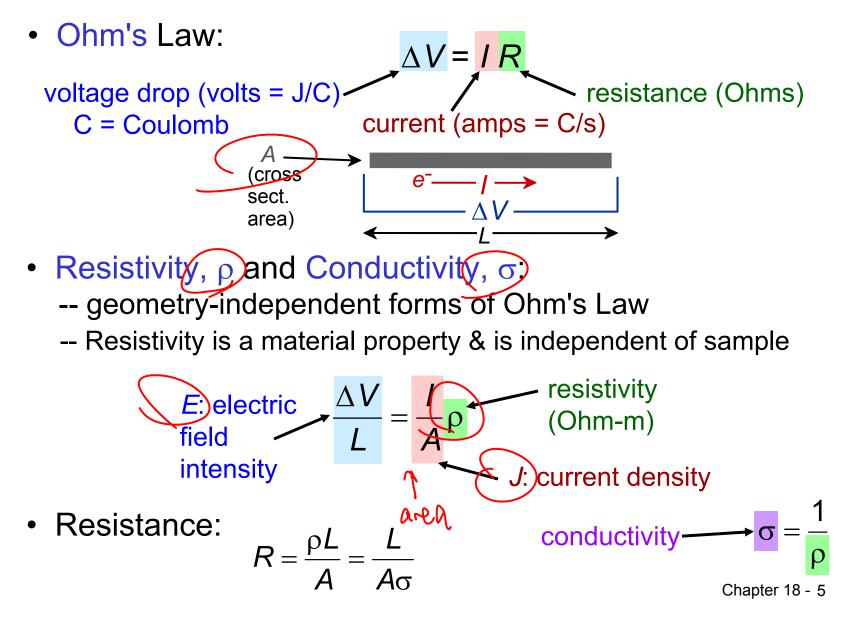
Fig. (d) from Fig. 18.27 (a), *Callister 7e*. (Fig. 18.27 is courtesy Nick Gonzales, National Semiconductor Corp., West Jordan, UT.)



Fig. (a), (b), (c) from Fig. 18.0, *Callister 7e*.

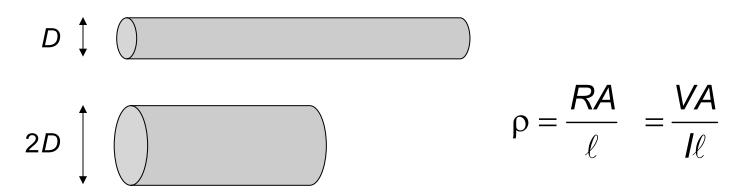
Chapter 18 - 4

Electrical Conduction



Electrical Properties

• Which will conduct more electricity?



- Analogous to flow of water in a pipe
- So resistance depends on sample geometry, etc.

Definitions

Further definitions

 $J = \sigma \varepsilon$ <= another way to state Ohm's law $J = \text{current density} = \frac{\text{current}}{\text{surface area}} = \frac{1}{A} \quad \text{like a flux}$ $\varepsilon = \text{electric field potential} = V/\ell \quad \text{or} \quad (\Delta V/\Delta \ell)$ $J = \sigma (\Delta V/\Delta \ell)$ Electron flux conductivity voltage gradient

Current carriers

- electrons in most solids
- ions can also carry (particularly in liquid solutions)

Conductivity: Comparison

• Room T values (Ohm-m) ⁻¹ = (Ω - m) ⁻¹					
METALS	conductors	CERAMICS			
Silver	6.8 x 10 ⁷	Soda-lime glass	10 ⁻¹⁰ -10 ⁻¹¹		
Copper	6.0 x 10 ⁷	Concrete	10 ⁻⁹		
Iron	1.0 x 10 ⁷	Aluminum oxide	<10 ⁻¹³		

SEMICOND	UCTO	ORS	
Silicon	4 x	10 ⁻⁴	
Germanium	2 x	10 ⁰	
GaAs		10 ⁻⁶	
	semio	condu	uctors

POLYMERS Polystyrene Polyethylene

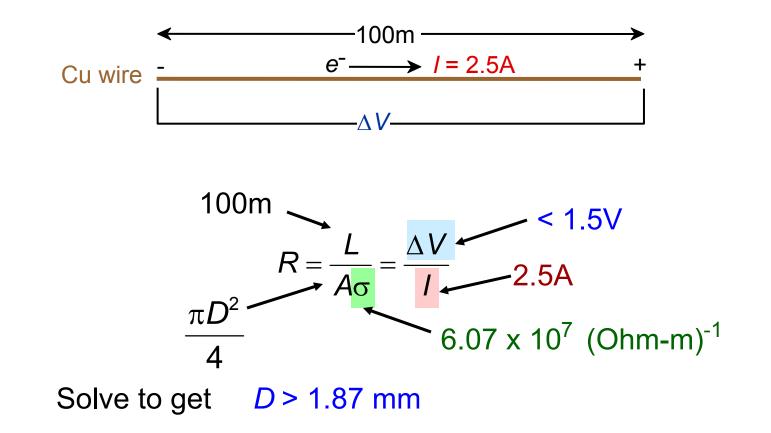
<10⁻¹⁴ 10⁻¹⁵-10⁻¹⁷

insulators

Selected values from Tables 18.1, 18.3, and 18.4, Callister 7e.

Example: Conductivity Problem

What is the minimum diameter (*D*) of a Cu wire so that $\Delta V < 1.5 V$?

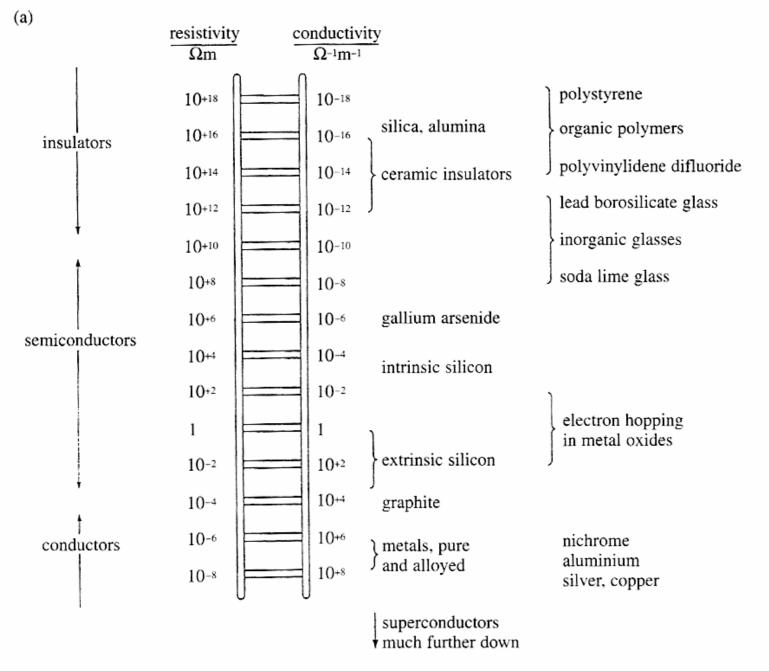


Callister 18.17

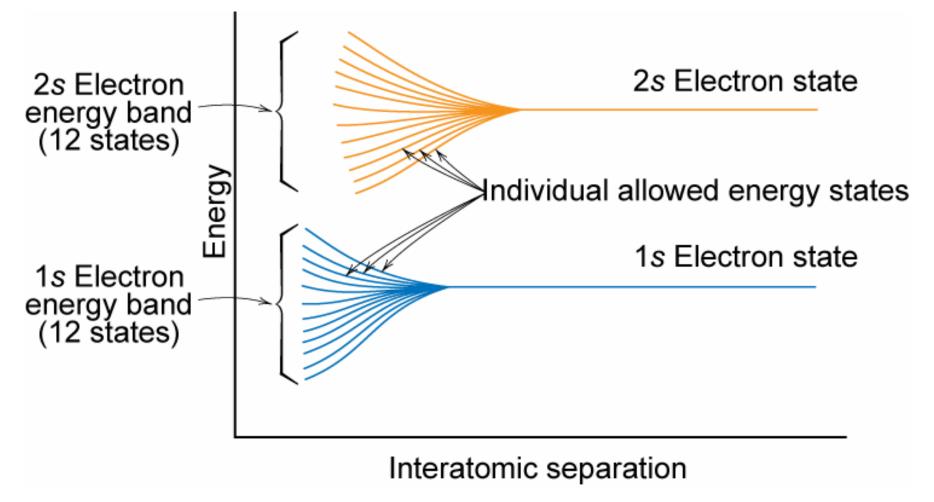
 A cylindrical metal wire 3 mm in diameter is required to carry a current of 12 A with a minimum of 0.01 V drop per foot (300 mm) of wire. Which of the metals and alloys listed in Table 18.1 are possible candidates?

Table 18.1 Room-Temperature Electrical Conductivities for Nine Common Metals and Alloys

Metal	Electrical Conductivity $[(\Omega - m)^{-1}]$		
Silver	6.8×10^{7}		
Copper	6.0×10^{7}		
Gold	4.3×10^{7}		
Aluminum	3.8×10^{7}		
Brass (70Cu-30Za)	1.6×10^{7}		
Iron	1.0×10^{7}		
Platinum	0.94×10^{7}		
Plain carbon steel	0.6×10^{7}		
Stainless steel	0.2×10^{7}		



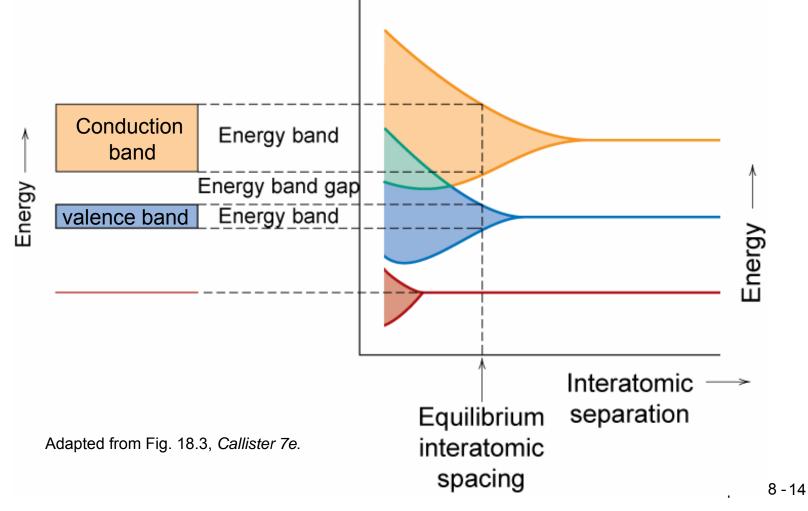
Electronic Band Structures



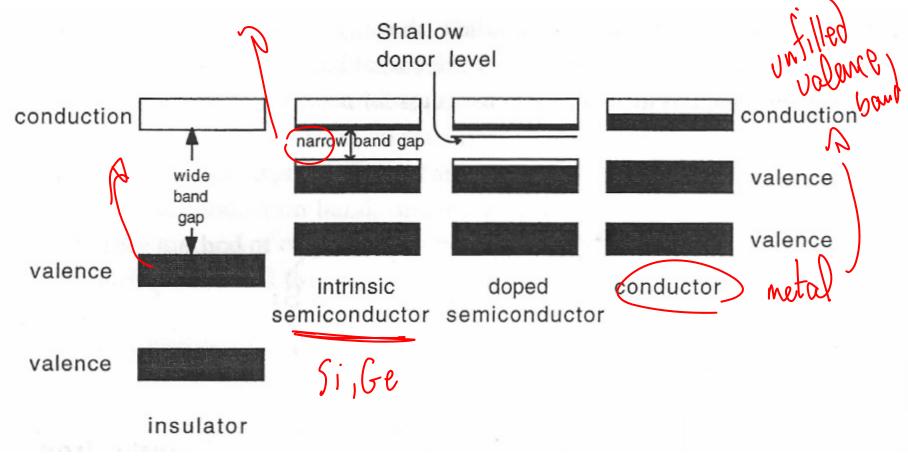
Adapted from Fig. 18.2, Callister 7e.

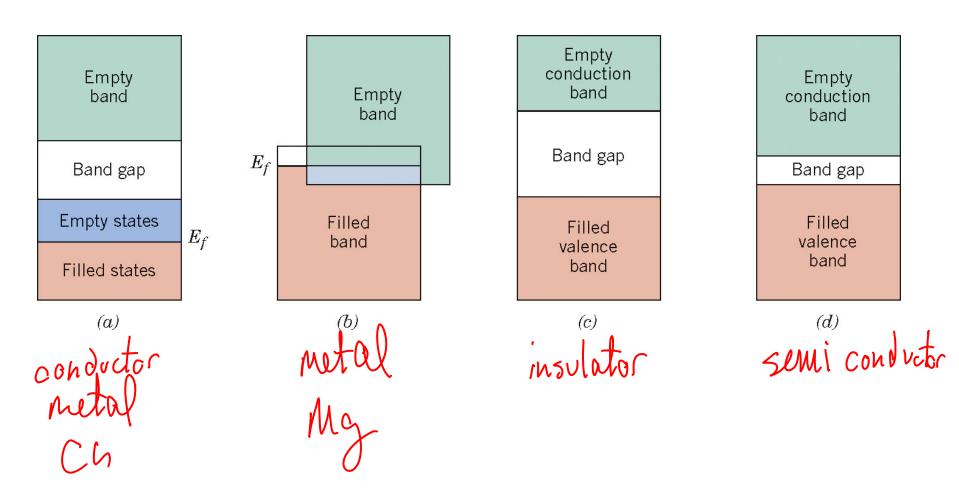
Band Structure

- Valence band filled highest occupied energy levels
- Conduction band empty lowest unoccupied energy levels



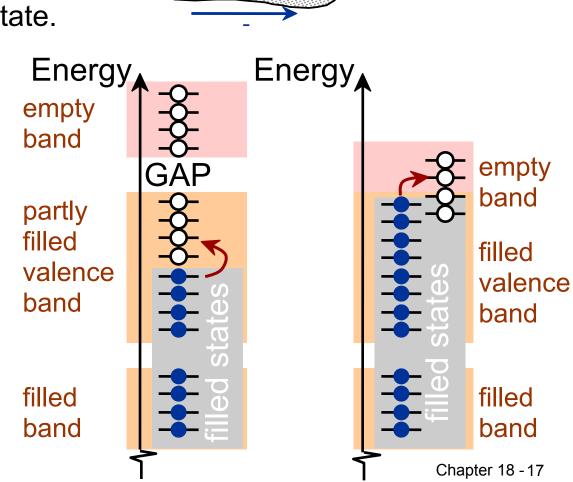
22eV





Conduction & Electron Transport

- Metals (Conductors):
- -- Thermal energy puts many electrons into a higher energy state.
- Energy States:
- -- for metals nearby energy states are accessible by thermal fluctuations.

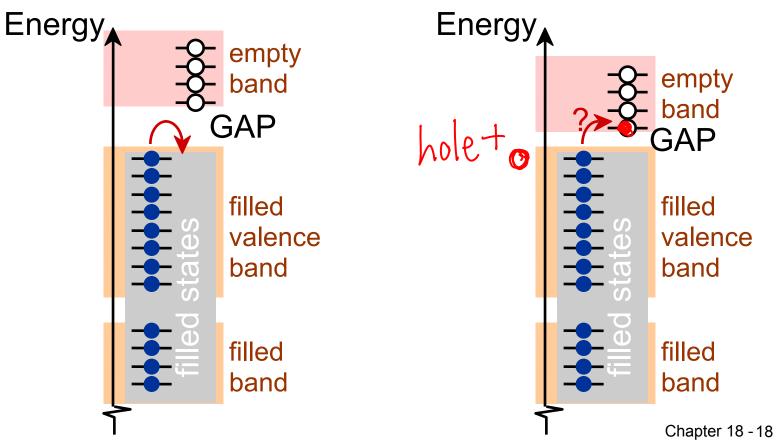


+

Energy States: Insulators & Semiconductors

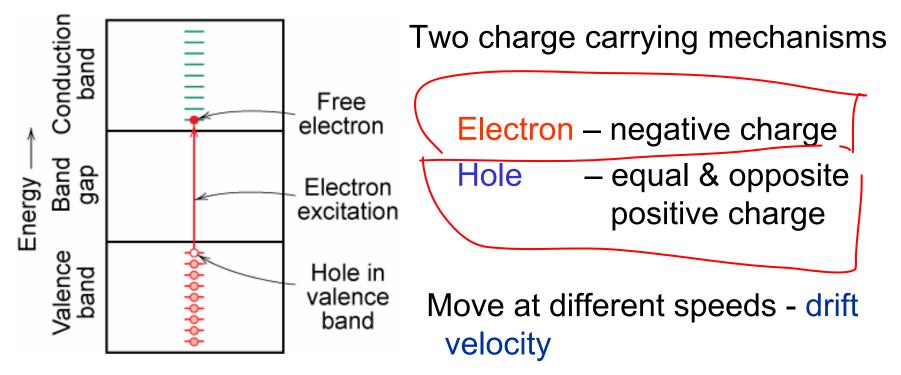
• Insulators:

- Semiconductors:
- -- Higher energy states not -- Higher energy states separated accessible due to gap (> 2 eV). by smaller gap (< 2 eV).



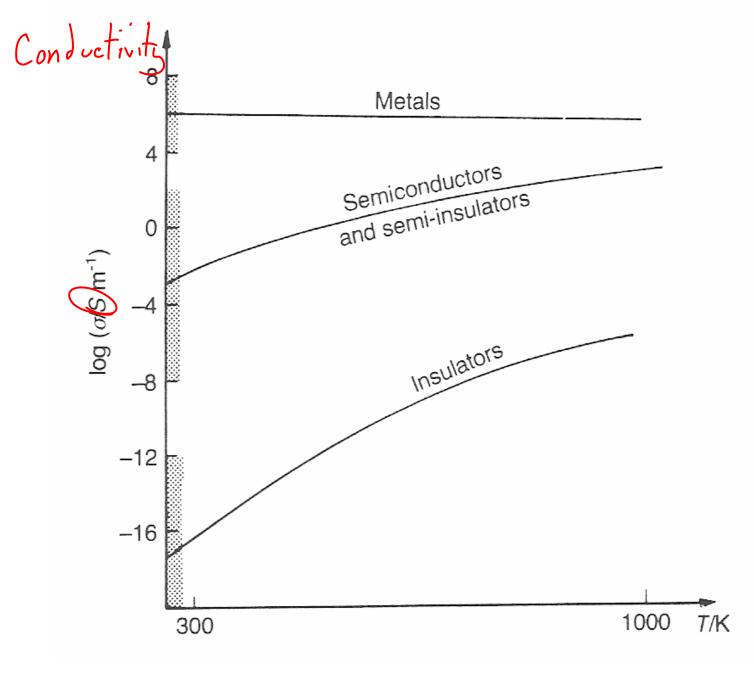
Charge Carriers

Adapted from Fig. 18.6 (b), Callister 7e.



Higher temp. promotes more electrons into the conduction band

Electrons scattered by impurities, grain boundaries, etc.

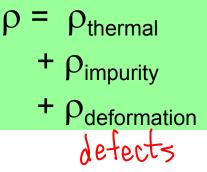


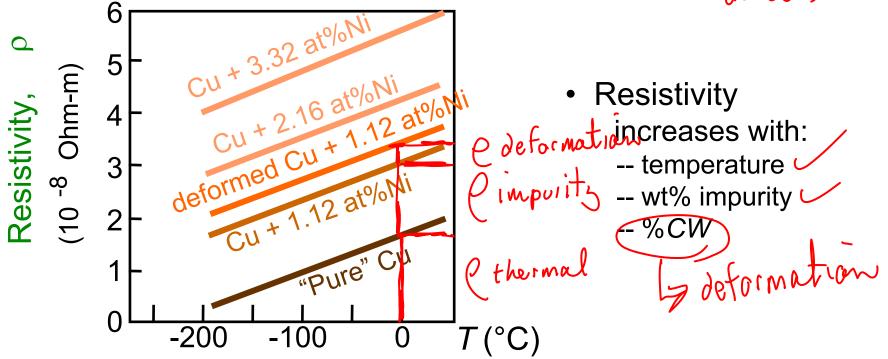
Chapter 18 - 20

Metals: Resistivity vs T, Impurities

- Imperfections increase resistivity
 - -- grain boundaries
 - -- dislocations
 - -- impurity atoms
 - -- vacancies

These act to scatter electrons so that they take a less direct path.

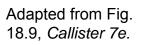


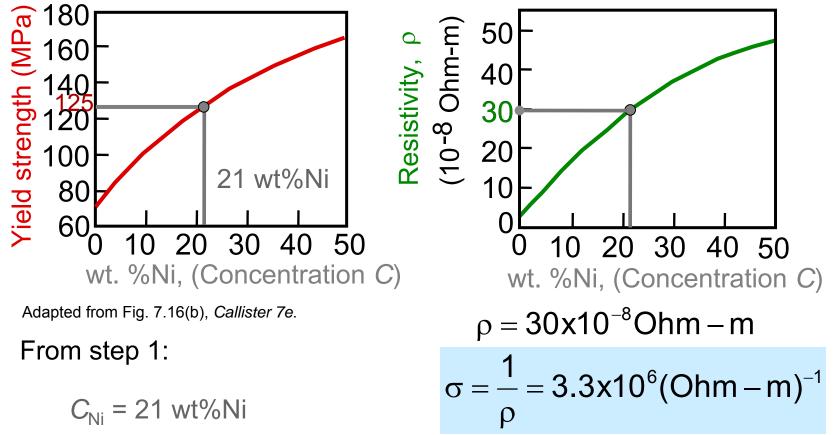


Adapted from Fig. 18.8, *Callister 7e*. (Fig. 18.8 adapted from J.O. Linde, *Ann. Physik* **5**, p. 219 (1932); and C.A. Wert and R.M. Thomson, *Physics of Solids*, 2nd ed., McGraw-Hill Book Company, New York, 1970.)

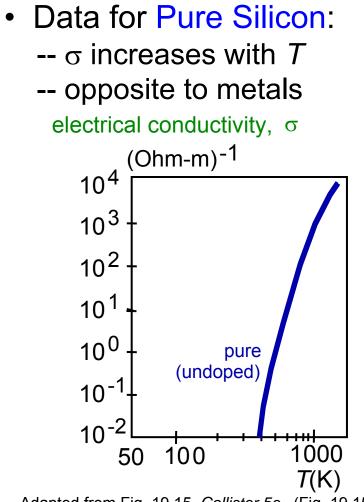
Estimating Conductivity

- Question:
 - -- Estimate the electrical conductivity σ of a Cu-Ni alloy that has a yield strength of 125 MPa.

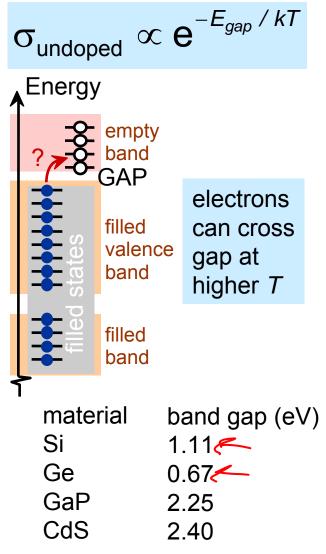




Pure Semiconductors: Conductivity vs T



Adapted from Fig. 19.15, *Callister 5e.* (Fig. 19.15 adapted from G.L. Pearson and J. Bardeen, *Phys. Rev.* **75**, p. 865, 1949.)



Selected values from Table 18.3, *Callister 7e*.

Intrinsic Semiconductors

- Pure material semiconductors: e.g., silicon & germanium
 - Group IVA materials
- Compound semiconductors
 - III-V compounds
 - Ex: GaAs & InSb
 - II-VI compounds
 - Ex: CdS & ZnTe
 - The wider the electronegativity difference between the elements the wider the energy gap.

Conduction in Terms of Electron and Hole Migration

 Concept of electrons and holes: valence electron • hole • electron • hole • Si atom electron pair creation pair migration applied applied no applied electric field electric field electric field Adapted from Fig. 18.11, • Electrical Conductivity given by: Callister 7e. # holes/m³ $\sigma = n e \mu_e +$ peµ_h hole mobility electron mobility # electrons/m

Number of Charge Carriers

Intrinsic Conductivity

 $\sigma = n|e|\mu_e + p|e|\mu_e|_{\mathsf{N}}$

Table 18.3

for intrinsic semiconductor n = p

$$\sigma = n|e|(\mu_e + \mu_n)$$

• Ex: GaAs

$$n = \frac{\sigma}{|e|(\mu_e + \mu_n)} = \frac{10^{-6} (\Omega \cdot m)^{-1}}{(1.6x10^{-19} \text{ C})(0.85 + 0.45 \text{ m}^2/\text{V} \cdot \text{s})}$$

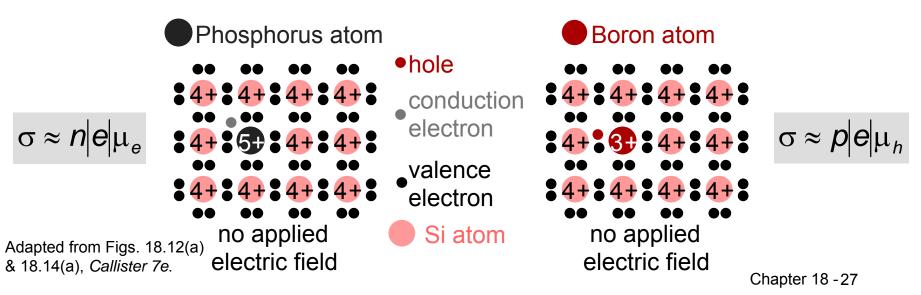
For GaAs $n = 4.8 \times 10^{24} \text{ m}^{-3}$
For Si $n = 1.3 \times 10^{16} \text{ m}^{-3}$

Intrinsic vs Extrinsic Conduction

• Intrinsic:

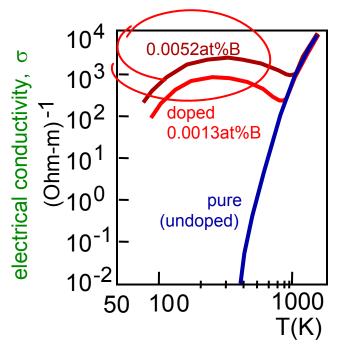
electrons = # holes (n = p)
--case for pure Si

- Extrinsic:
 - *--n≠ p*
 - --occurs when impurities are added with a different # valence electrons than the host (e.g., Si atoms)
- *n*-type Extrinsic: (n >> p)
 p-type Extrinsic: (p >> n)



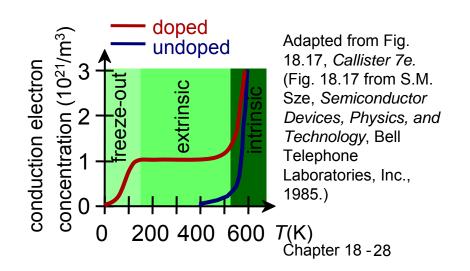
Doped Semiconductor: Conductivity vs. T

- Data for Doped Silicon:
 - -- $\boldsymbol{\sigma}$ increases doping
 - -- reason: imperfection sites lower the activation energy to produce mobile electrons.



Adapted from Fig. 19.15, *Callister 5e*. (Fig. 19.15 adapted from G.L. Pearson and J. Bardeen, *Phys. Rev.* **75**, p. 865, 1949.)

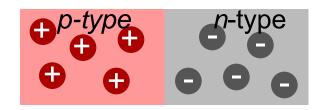
- Comparison: intrinsic vs extrinsic conduction...
 - -- extrinsic doping level:
 - 10²¹/m³ of a *n*-type donor impurity (such as P).
 - for T < 100 K: "freeze-out", thermal energy insufficient to excite electrons.
 - -- for 150 K < *T* < 450 K: "extrinsic"
 - -- for T >> 450 K: "intrinsic"

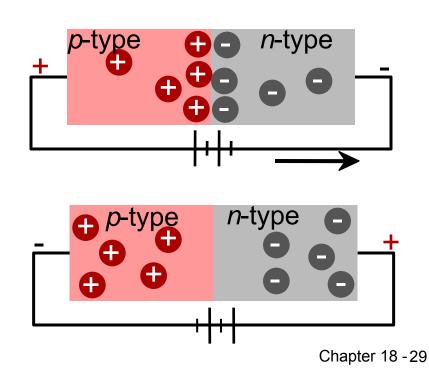


p-n Rectifying Junction

- Allows flow of electrons in one direction only (e.g., useful to convert alternating current to direct current.
- Processing: diffuse P into one side of a B-doped crystal.
- Results:

- Adapted from Fig. 18.21, *Callister 7e*.
- --No applied potential: no net current flow.
- --Forward bias: carrier flow through *p*-type and *n*-type regions; holes and electrons recombine at *p*-*n* junction; current flows.
- --Reverse bias: carrier flow away from *p*-*n* junction; carrier conc. greatly reduced at junction; little current flow.





Properties of Rectifying Junction

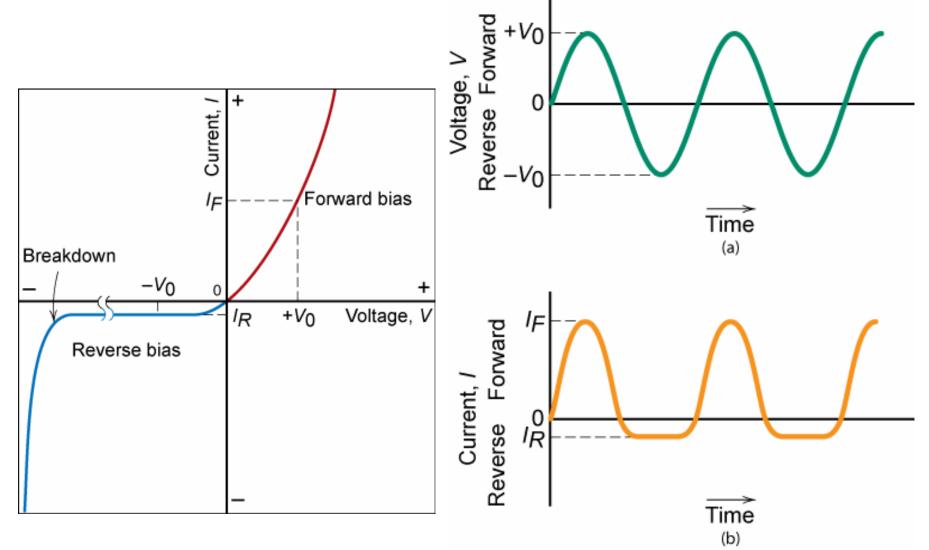
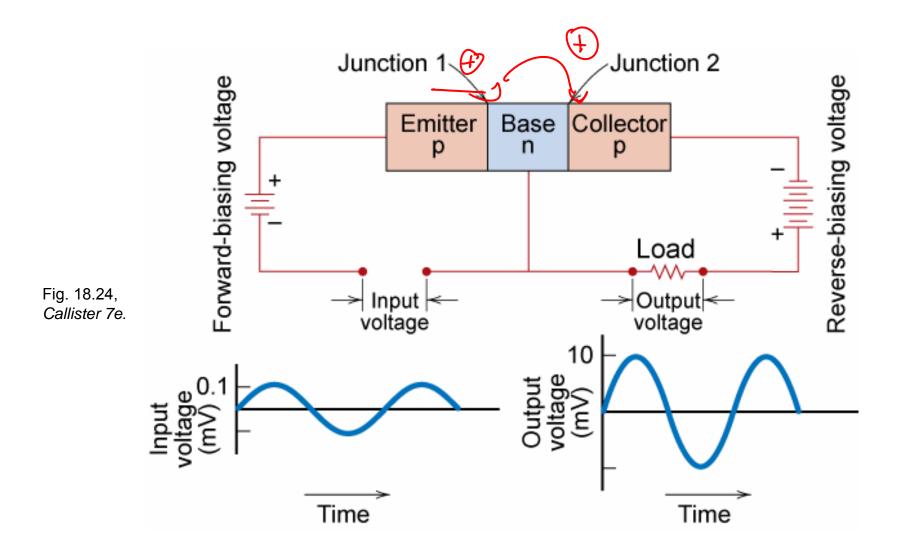


Fig. 18.22, Callister 7e.

Fig. 18.23, Callister 7e.

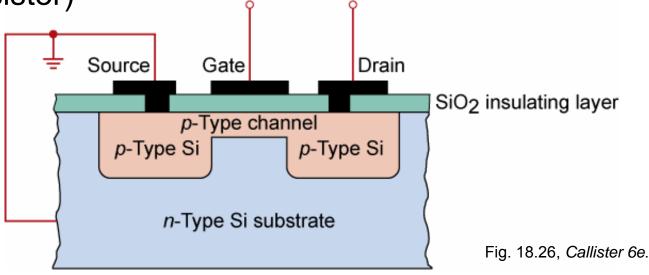
Chapter 18 - 30

Junction Transistor



Integrated Circuit Devices

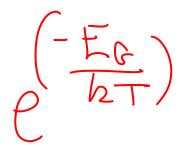
MOSFET (metal oxide semiconductor field effect ${\color{black}\bullet}$ transistor)



- Integrated circuits state of the art ca. 50 nm line • width
 - 1 Mbyte cache on board
 - > 100,000,000 components on chip
 - Al is the "wire" Cu is used a (0+ NOW Chant - chip formed layer by layer
 - Chapter 18 32

Summary

- Electrical conductivity and resistivity are:
 - -- material parameters.
 - -- geometry independent.
- Electrical resistance is:
 - -- a geometry and material dependent parameter.
- Conductors, semiconductors, and insulators...
 - -- differ in accessibility of energy states for conductance electrons.
- · For metals, conductivity is increased by
 - -- reducing deformation
 - -- reducing imperfections
 - -- decreasing temperature.
- For pure semiconductors, conductivity is increased by
 - -- increasing temperature
 - -- doping (e.g., adding B to Si (*p*-type) or P to Si (*n*-type).



Next time, Insulators (traditionally)

- Ceramics
 - Some structure
 - Capacitance, Dielectric properties
 - Ionic conduction
- Polymers
 - A bit on structure
 - Conducting polymers